

ABSTRACT OF THE DISCLOSURE

To form through electrodes effectively without deteriorating the quality of the through electrodes. A semiconductor substrate 1 is spin etched at its back surface 1", thereby thinning down the semiconductor substrate 1, making opening sections 3 penetrate the semiconductor substrate 1, and forming through holes 3 in the semiconductor substrate 1. Tips of embedded electrodes 7 are exposed out of the through holes 3 in the semiconductor substrate 1, to form through electrodes 7'.